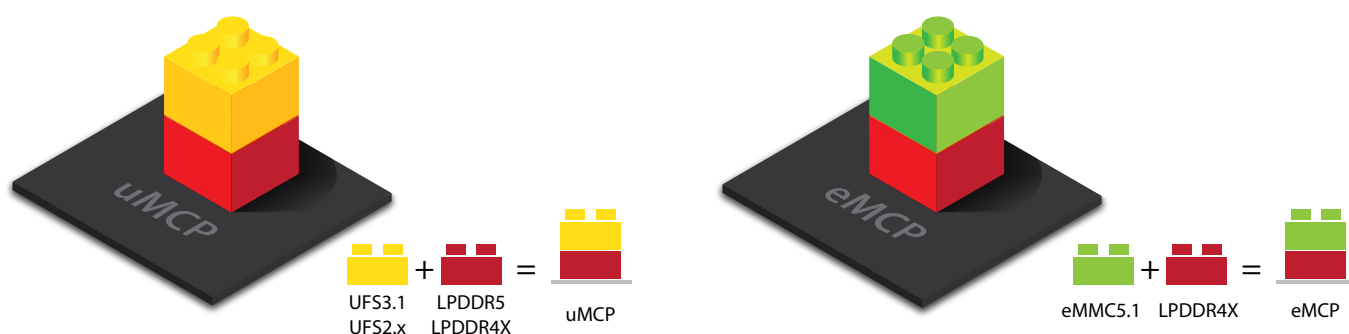


# MCP

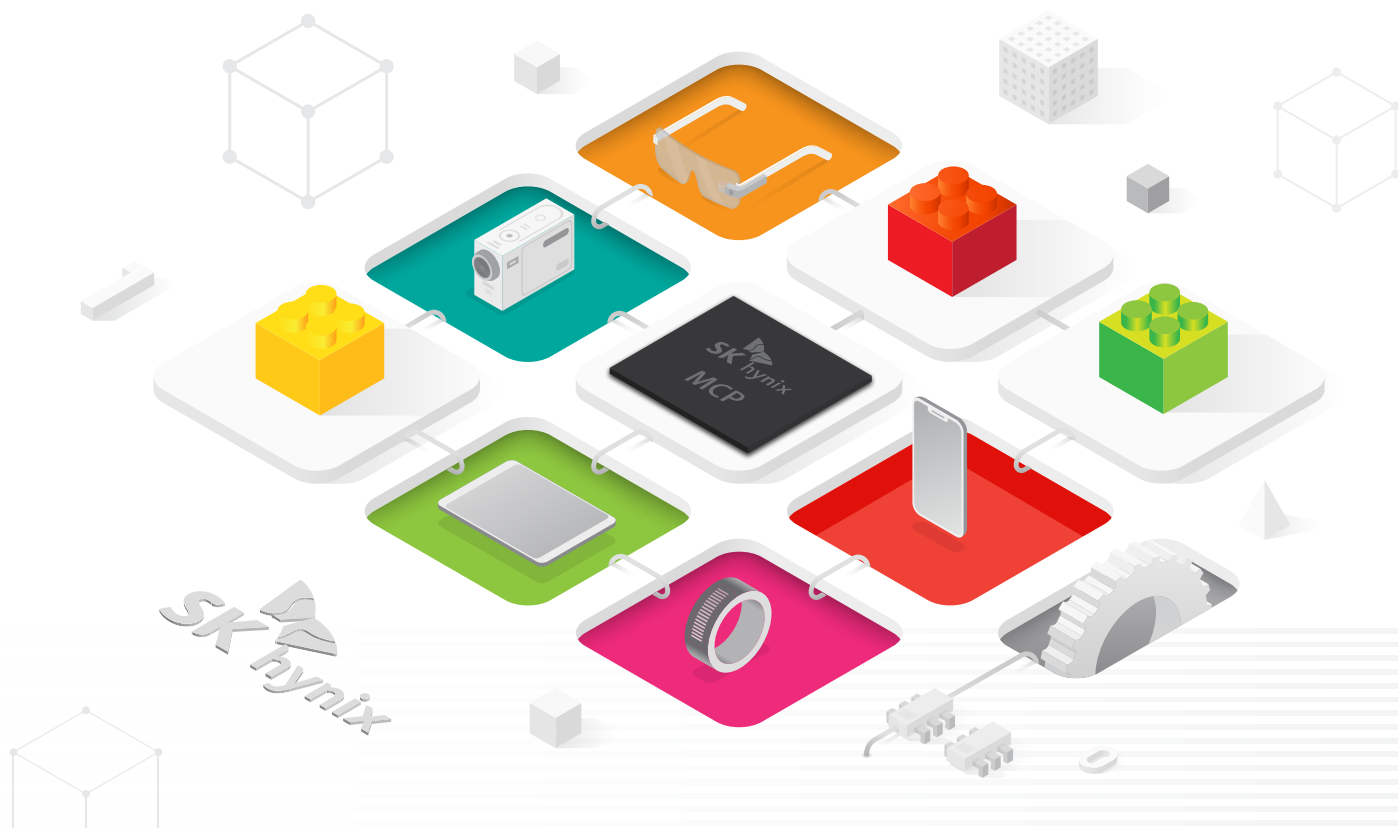
Multiplayer with DRAM and NAND Controller in One!

Multi Chip Package (MCP) is the ultimate solution for mobile devices, combining UFS or eMMC storage and LPDDR memory in a single area-efficient package that achieves high densities and ultra-fast speeds.

## More to Expect



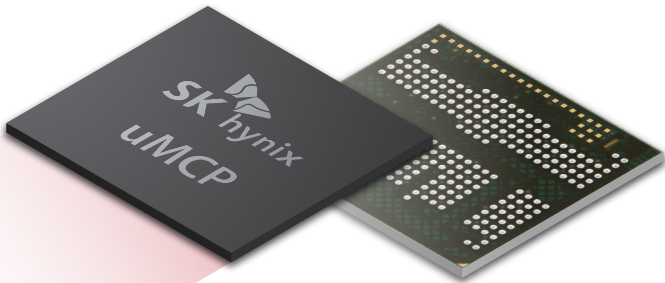
An MCP can realize 40-50% space saving gains compared to discrete DRAM and NAND. This advantage continues to drive MCP adoption in high-density mobile storage, where the lineup of uMCPs is ever-expanding on top of a broad portfolio of eMCPs that continue to fulfill a wide range of capacity and power requirements.



# Product Details

## | uMCP

- UFS NAND and LPDDR DRAM stacked in a single package
- Competitively thin form factor packing high densities with smaller footprint

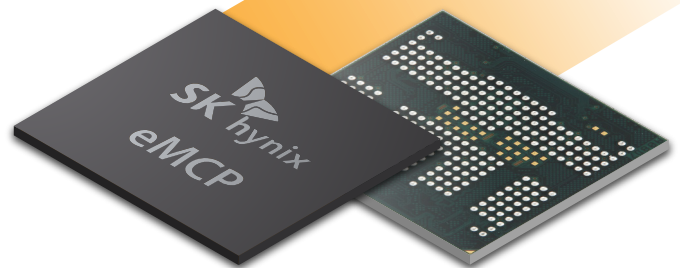


NAND mode	UFS2.x, UFS3.x
NAND Density	Up to 512GB
DRAM mode	LPDDR4X, LPDDR5
DRAM Density	Up to 12GB
Speed	4266Mbps(LPDDR4X), 6400Mbps(LPDDR5)
Package type	254ball(LPDDR4X), 297ball(LPDDR5)

## | eMCP

- eMMC NAND and LPDDR DRAM stacked in a single package
- Realizes 40% better space efficiency for mobile devices

NAND mode	eMMC5.1
NAND Density	Up to 128GB
DRAM mode	LPDDR4X
DRAM Density	Up to 6GB
Speed	4266Mbps
Package type	254Ball



# Use Cases

